

Title (en)  
METHOD AND DEVICE FOR PLASMA TREATMENT OF A FLAT SUBSTRATE

Title (de)  
VERFAHREN UND VORRICHTUNG ZUR PLASMABEHANDLUNG EINES FLACHEN SUBSTRATS

Title (fr)  
PROCÉDÉ ET DISPOSITIF DE TRAITEMENT AU PLASMA D'UN SUBSTRAT PLAT

Publication  
**EP 2351064 A1 20110803 (DE)**

Application  
**EP 09765014 A 20091104**

Priority  

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Abstract (en)  
[origin: WO2010051982A1] Method and device for the plasma treatment of a substrate in a plasma device, wherein - the substrate (110) is arranged between an electrode (112) and a counter-electrode (108) having a distance d between a surface area of the substrate to be treated and the electrode, - a capacitively coupled plasma discharge is excited, forming a DC self-bias between the electrode (112) and the counter-electrode (108), - in an area of the plasma discharge between the surface area to be treated and the electrode having a quasineutral plasma bulk (114), a quantity of at least one activatable gas species, to which a surface area of the substrate to be treated is subjected, is present - it is provided that a plasma discharge is excited, - wherein the distance d has a value comparable to  $s = s_e + s_g$ , where  $s_e$  denotes a thickness of a plasma boundary layer (119) in front of the electrode, and  $s_g$  denotes a thickness of a plasma boundary layer (118) in front of the substrate surface to be treated or - wherein the quasineutral plasma bulk (114) between the surface area to be treated and the electrode has a linear extension  $d_p$ , where  $d_p < 1/3d$ ,  $d_p < \max(s_e + s_g)$  or  $d_p < 0.5s$ .

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